

**Features:**

- Isolated mounting base 4000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

**Typical Applications:**

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

V <sub>RRM</sub> , V <sub>DRM</sub>	Type & Outline		
	2600V	MTx135-26-216F3	MTx135-26-216F3B
2800V	MTx135-28-216F3	MTx135-28-216F3B	
3000V	MTx135-30-216F3	MTx135-30-216F3B	
3200V	MTx135-32-216F3	MTx135-32-216F3B	
3400V	MTx135-34-216F3	MTx135-34-216F3B	
3600V	MTx135-36-216F3	MTx135-36-216F3B	
3600V		MTx135-36-216F3BG	

MTx stands for any type of **MTC**, **MTA**, **MTK**

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>j</sub> (°C)	VALUE			UNIT
				Min	Type	Max	
I <sub>T(AV)</sub>	Mean on-state current	180° half sine wave 50Hz Single side cooled, T <sub>C</sub> =85°C	125			135	A
I <sub>T(RMS)</sub>	RMS on-state current					212	A
I <sub>DRM</sub> I <sub>RRM</sub>	Repetitive peak current	at V <sub>DRM</sub> at V <sub>RRM</sub>	125			25	mA
I <sub>TSM</sub>	Surge on-state current	V <sub>R</sub> =60%V <sub>RRM</sub> , t=10ms half sine	125			2.6	kA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination		125			34	10 <sup>3</sup> A <sup>2</sup> s
V <sub>TO</sub>	Threshold voltage		125			0.88	V
r <sub>T</sub>	On-state slope resistance					2.40	mΩ
V <sub>TM</sub>	Peak on-state voltage	I <sub>TM</sub> =410A	25			2.58	V
dv/dt	Critical rate of rise of off-state voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125			1000	V/μs
di/dt	Critical rate of rise of on-state current	Gate source 1.5A t <sub>r</sub> ≤0.5μs Repetitive	125			200	A/μs
I <sub>GT</sub>	Gate trigger current	VA=12V, I <sub>A</sub> =1A	25	30		150	mA
V <sub>GT</sub>	Gate trigger voltage			0.8		2.5	V
I <sub>H</sub>	Holding current			10		200	mA
I <sub>L</sub>	Latching current					1000	mA
V <sub>GD</sub>	Non-trigger gate voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125			0.20	V
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	Single side cooled per chip				0.18	°C/W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	Single side cooled per chip				0.08	°C/W
V <sub>iso</sub>	Isolation voltage	50Hz,R.M.S,t=1min,I <sub>iso</sub> :1mA(MAX)		4000			V
F <sub>m</sub>	Terminal connection torque(M6)			4.5		6	N·m
	Mounting torque(M6)			4.5		6	N·m
T <sub>vj</sub>	Junction temperature			-40		125	°C
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				320		g
Outline		216F3, 216F3B					

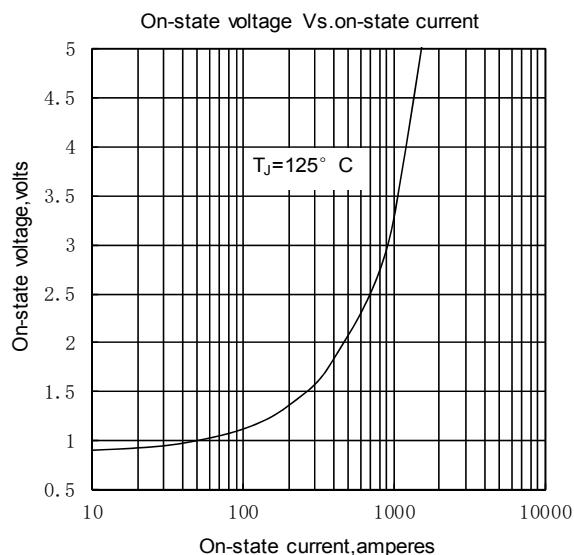


Fig.1

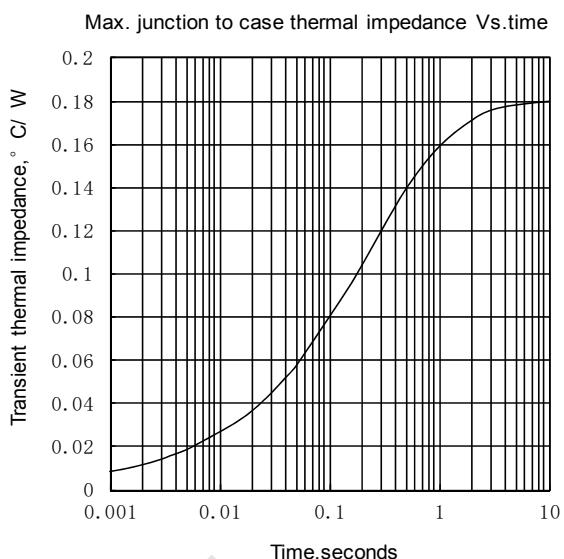


Fig.2

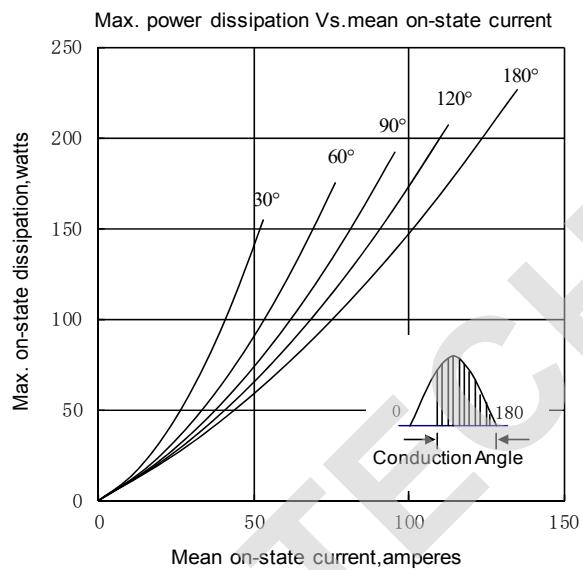


Fig.3

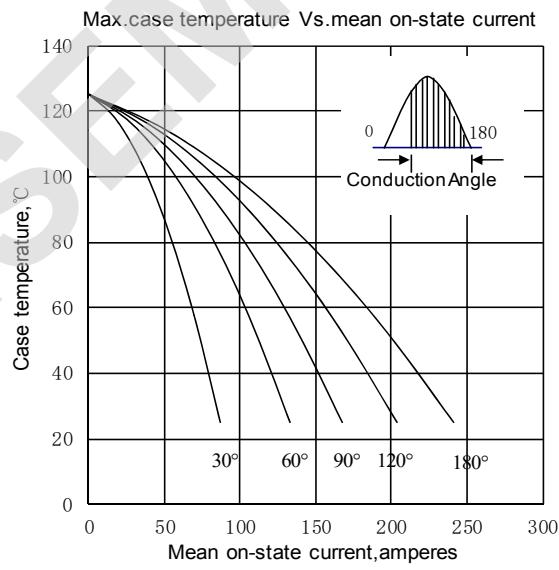


Fig.4

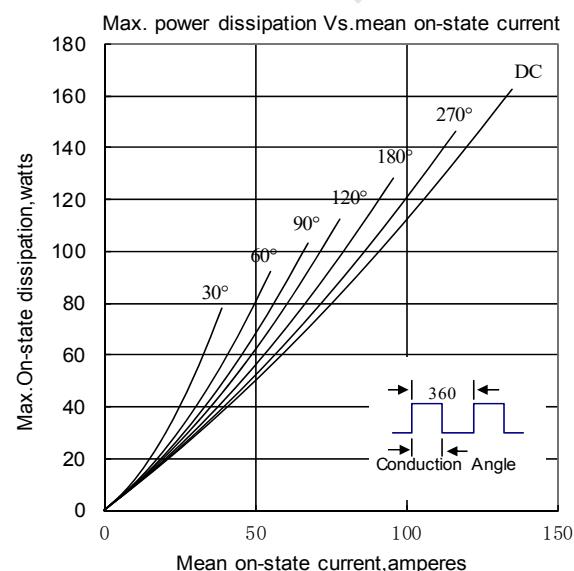


Fig.5

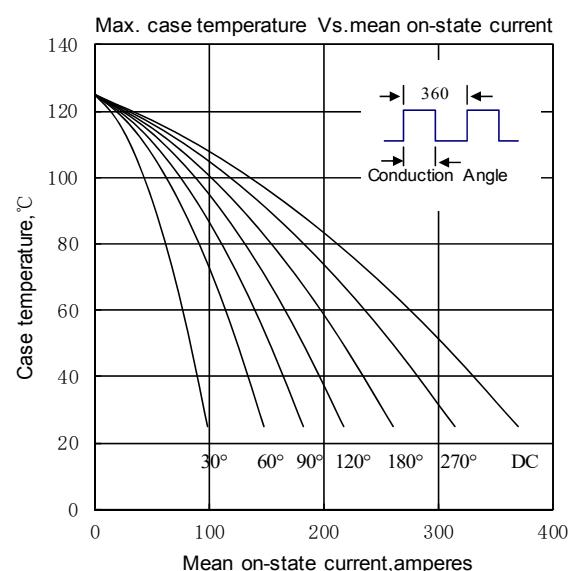


Fig.6

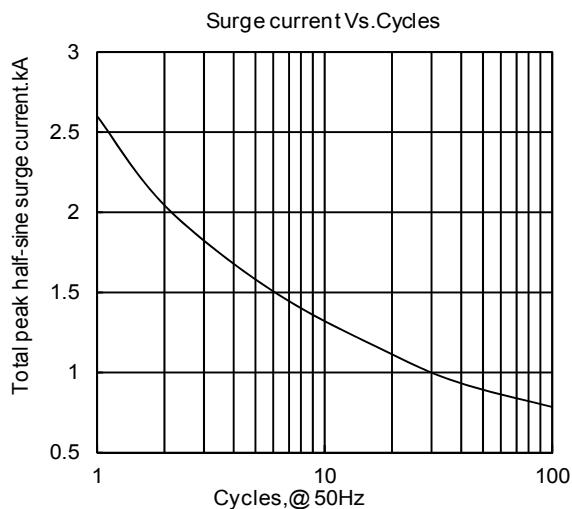


Fig. 7

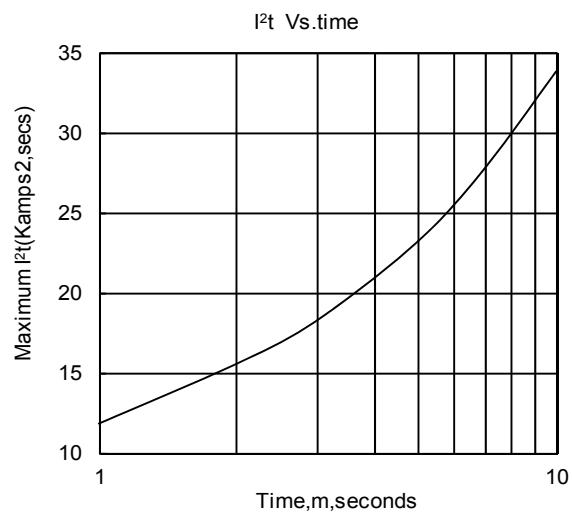


Fig. 8

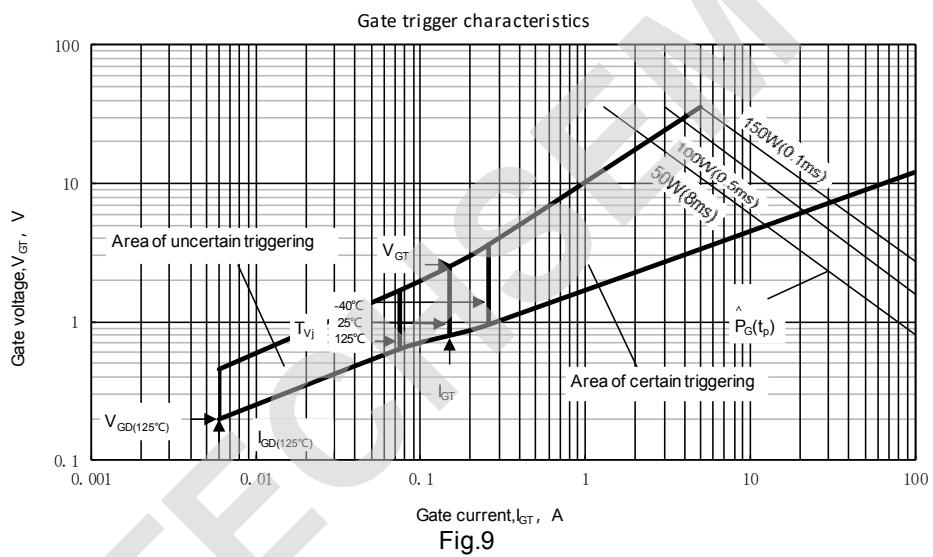
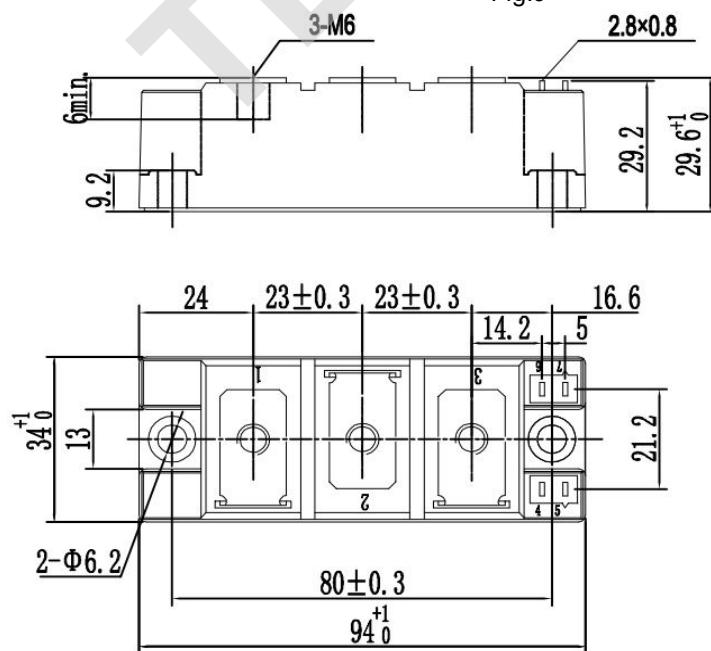


Fig.9

**Outline:****Unmarked dimensional tolerance: ±0.5mm**

TECHSEM reserves the right to change specifications without notice.

